



Attorney Docket No.: PATENT
COOL-01600

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	Group Art Unit: 1763
Thomas W. Kenny et al.)	Examiner:
Serial No.: 10/643,684)	<u>TRANSMITTAL LETTER</u>
Filed: August 18, 2003)	162 N. Wolfe Road
For: APPARATUS AND METHOD OF)	Sunnyvale, CA 94086
FORMING CHANNELS IN A)	(408) 530-9700
HEAT-EXCHANGING DEVICE)	Customer No.: 28960

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

Enclosed please find an Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #59981); (EFS ID #59982); (EFS ID #59983) and (EFS ID #59986) filed on April 28, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 4/29/04

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CERTIFICATE OF MAILING (37 CFR § 1.8(a))

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #59981); (EFS ID #59982); (EFS ID #59983) and (EFS ID #59986). Applicants have become aware of the following printed publication which may be material to the examination of this application:

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This Information Disclosure Statement under 37 C.F.R. §§ 1.56 and 1.97 is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that anyone or more of these citations constitutes prior art.

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 4-29-04

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Attorneys for Applicants

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Attorney Docket No.: COOL-01600

Serial No.: 10/643,684

INFORMATION DISCLOSURE STATEMENT BY APPLICANT
(Use Several Sheets If Necessary)

Applicants: Thomas W. Kenny et al.

(37 CFR § 1.98(b))

Filing Date: August 18, 2003

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Title of Invention

APPARATUS AND METHOD OF FORMING CHANNELS IN A HEAT-EXCHANGING DEVICE

Submission Type: Information Disclosure Statement

Application Number: 10/643684

10/643684

EFS ID: 59981

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Page 2 of 2

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Application Number:	10/643684	*10/643684*	
Date:	2003-08-18		
First Named Applicant:	Thomas Kenny		
Confirmation Number:	4600		
Attorney Docket Number:			
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Application Number: 10/643684

10/643684

Confirmation Number: 4600

First Named Applicant: Thomas Kenny

Attorney Docket Number:

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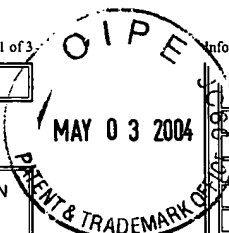
US Patent Documents

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	2	3817321	1974-06-18	von Cube et al.			
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Application Number:	10/643684	*10/643684*												
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Registered Number: 32571			

Documents being submitted	Files
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	us-ids.xsl
Comments	



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8

Stylesheet Version v1.8.0

Title of Invention	APPARATUS AND METHOD OF FORMING CHANNELS IN A HEAT-EXCHANGING DEVICE
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Application Number: 10/643684 *10/643684*

Confirmation Number: 4600

First Named Applicant: Thomas Kenny

Attorney Docket Number:

Search string: (5383340 or 5421943 or 5427174 or 5436793 or 5459099 or 5508234 or 5514832 or 5514906 or 5544696 or 5548605 or 5575929 or 5579828 or 5585069 or 5641400 or 5692558 or 5696405 or 5703536 or 5704416 or 5727618 or 5759014 or 5763951 or 5774779 or 5800690 or 5801442 or 5835345 or 5836750 or 5858188 or 5863708 or 5869004 or 5870823 or 5874795 or 5876655 or 5880017 or 5880524 or 5901037 or 5936192 or 5940270 or 5942093 or 5964092 or 5965001 or 5965813 or 5978220 or 5997713 or 5998240 or 6007309 or 6010316 or 6013164 or 6019882 or 6054034 or 6068752).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5383340	1995-01-24	Larson et al.			
	2	5421943	1995-06-06	Tam et al.			
	3	5427174	1995-06-27	Lomolino et al.			
	4	5436793	1995-07-25	Sanwo et al.			
	5	5459099	1995-10-17	Hsu			
	6	5508234	1996-04-16	Dusablon, Sr. et al.			
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8	5514906	1996-05-07	Love et al.
9	5544696	1996-08-13	Leland
10	5548605	1996-08-20	Benett et al.
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15	5692558	1997-12-02	Hamilton et al.
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21	5763951	1998-06-09	Hamilton et al.
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43	5997713	1999-12-07	Beetz, Jr. et al.
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46	6010316	2000-01-04	Haller et al.
47	6013164	2000-01-11	Paul et al.
48	6019882	2000-02-01	Paul et al.
49	6054034	2000-04-25	Soane et al.
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Signature

Examiner Name	Date

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Title of Invention	APPARATUS AND METHOD OF FORMING CHANNELS IN A HEAT-EXCHANGING DEVICE													
Submission Type:	Information Disclosure Statement													
Application Number:	10/643684	*10/643684*												
EFS ID:	59983													
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ISYS5	Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmaton/Application numbers at this time. They will be checked by PTO personnel later.													
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Attorney Docket Number:														
Timestamp:	2004-04-28 14:28:45 EDT													
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TRANSMITTAL

Electronic Version v1.1
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Title of Invention	APPARATUS AND METHOD OF FORMING CHANNELS IN A HEAT-EXCHANGING DEVICE		
Application Number:	10/643684	*10/643684*	
Date:	2003-08-18		
First Named Applicant:	Thomas Kenny		
Confirmation Number:	4600		
Attorney Docket Number:			
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>			
Submitted by:		Elec. Sign.	Sign. Capacity
Thomas B. Haverstock		/tbh/	Attorney
Registered Number: 32571			

Documents being submitted	Files
us-ids	COOL01600C-usidst.xml
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Comments	



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of
InventionAPPARATUS AND METHOD OF FORMING CHANNELS IN
A HEAT-EXCHANGING DEVICE

Application Number: 10/643684

10/643684

Confirmation Number: 4600

First Named Applicant: Thomas Kenny

Attorney Docket Number:

Search string: (6090251 or 6096656 or 6100541 or 6101715
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or 6553253 or 6572749 or 6588498 or
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US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6090251	2000-07-18	Sundberg et al.			
	2	6096656	2000-08-01	Matzke et al.			
	3	6100541	2000-08-08	Nagle et al.			
	4	6101715	2000-08-15	Fuesser et al.			
	5	6119729	2000-09-19	Oberholzer et al.			
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33	6388317	2002-05-14	Reese	B1
34	6396706	2002-05-28	Wohlfarth	B1
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43	6457515	2002-10-01	Vafai et al.	B1
44	6495015	2002-12-17	Schoeniger et al.	B1
45	6537437	2003-03-25	Galambos et al.	B1
46	6543521	2003-04-08	Sato et al.	B1
47	6553253	2003-04-22	Chang	B1
48	6572749	2003-06-03	Paul et al.	B1
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Signature

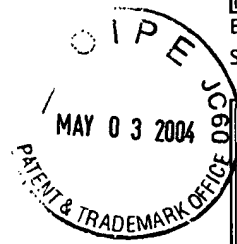
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Date

**UNITED STATES PATENT AND TRADEMARK OFFICE
ACKNOWLEDGEMENT RECEIPT**

Electronic Version 1.1

Stylesheet Version v1.1.1



Title of Invention	APPARATUS AND METHOD OF FORMING CHANNELS IN A HEAT-EXCHANGING DEVICE													
Submission Type:	Information Disclosure Statement													
Application Number:	10/643684	*10/643684*												
EFS ID:	59986													
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Attorney Docket Number:														
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TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	APPARATUS AND METHOD OF FORMING CHANNELS IN A HEAT-EXCHANGING DEVICE		
Application Number:	10/643684	*10/643684*	
Date:	2003-08-18		
First Named Applicant:	Thomas Kenny		
Confirmation Number:	4600		
Attorney Docket Number:			
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Submitted by:		Elec. Sign.	Sign. Capacity
Thomas B. Haverstock		/tbh/	Attorney
Registered Number: 32571			

Documents being submitted	Files
us-ids	COOL01600D-usidst.xml
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Comments	



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Title of
InventionAPPARATUS AND METHOD OF FORMING CHANNELS IN
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Application Number: 10/643684

10/643684

Confirmation Number: 4600

First Named Applicant: Thomas Kenny

Attorney Docket Number:

Search string: (6632655 or 20010016985 or 20010024820 or
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20020011330 or 20020134543).pn.**US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6632655	2003-10-14	Mehta et al.	B1		

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

Init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20010016985	2001-08-30	Insley et al.	A1		
	2	20010024820	2001-09-27	Mastromatteo et al.	A1		
	3	20010044155	2001-11-22	Paul et al.	A1		
	4	20010045270	2001-11-29	Bhatti et al.	A1		
	5	20010046703	2001-11-29	Burns et al.	A1		
	6	20010055714	2001-12-27	Cettour-Rose et al.	A1		
	7	20020011330	2002-01-31	Insley et al.	A1		
	8	20020134543	2002-09-26	Estes et al.	A1		

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